

## **AMENDMENTS TO THE CLAIMS**

**1-17. (Canceled)**

**18. (Previously Presented)** A photosensitive material for photolithographic patterning which comprises, as an integral layered body:

(a) a substrate; and

(b) a photoresist layer having a thickness in the range of from 100 to 570 nm formed on the surface of the substrate from a chemical-amplification positive-working photoresist composition which comprises as a uniform solution in an organic solvent:

an organic-acid generating compound capable of generating an acid by the irradiation with actinic rays;

a resinous composition having acid-dissociable groups and capable of being imparted with increased solubility in an aqueous alkaline solution by interaction with an acid; and

a surface active agent in a concentration lower than 10 ppm by weight based on the amount of the resinous composition and

(c) said substrate, prior to the formation of said photoresist layer, having an adsorbent thereon for said surface active agent.